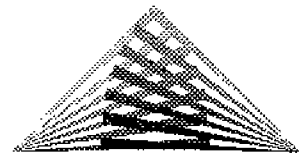


# Optical Communication Devices and Materials for Planar Waveguide Circuits



**ZENPHOTONICS**

Seon Gyu Han

(주) 젠포토닉스

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## Contents

- WDM Optical Network
- Material for Optical Networks
- Polymers for Optical Devices  
(ZEN, ETRI)
- Optical Devices with Dolymer  
(ZEN, ETRI)

## Introduction

### Telecommunication Evolution

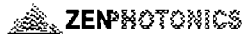
1950	1980	2010
Electron	Photon	
TDM	WDM	100Mbps
Analog	Digital	Internet
Voice	Data	400 times

*Photon has higher carrier speed*

*Photon has a unique property.....more wavelength --> more information*

*Digital process --> clean and higher information*

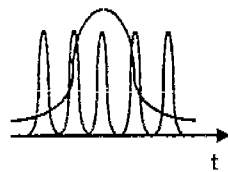
*Voice : Data 1:1 --> 1:20 (2010)*



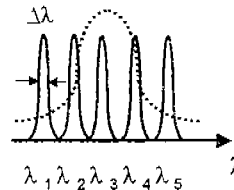
3

## WDM Communication

- different wavelength not interfere each other
- ultrafast time tech.  $\Rightarrow$  multi wavelength tech.
- Low speed data controll  $\Rightarrow$  Low cost electronics
- High capacity data controll ( $>T$  bit/s)
- $\bullet \bullet \bullet$  data  $\bullet$
- multiwavelength tech ..... Prism, Fabry-Parot, Mach-Zehnder, AWG



**TDM**  
(Time Division Multiplexing)



**WDM**  
(Wavelength Division Memultiplexing)



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## WDM Key Devices

• **Discret Devices**

- Source, Detector, Optical Fiber, Modulator, OXC Optical Switch, (Variable)Attenuator, splitter
- Wavelength Mux/Demux, Wavelength (tunable) Filter
- Amplifier, All optical devices( $\chi^{(3)}$ )

• **Integrated Devices**

- ADM(Add/Drop Multiplexer), Wavelength Selector , Wavelength Converter, 3R(Re-amplification, Re-shaping, Re-timing) Repeater

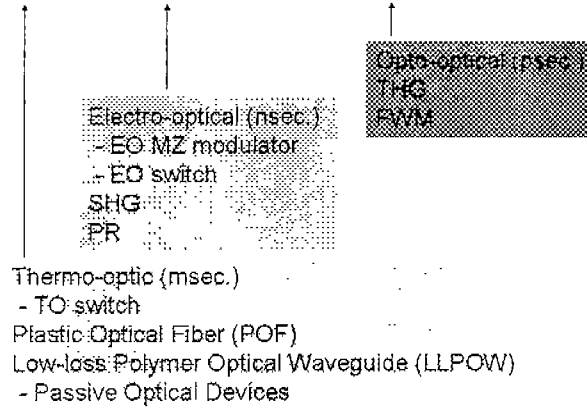
- RACE : 57 Devices
- ACTS : 54 Devices

## Material for optical system

Material	Process	Strong Point	Weakness
Polymer	Spin coating on smooth surfaces	<ul style="list-style-type: none"> <li>• simple process</li> <li>• low loss: &lt;0.02 dB/cm</li> <li>• low coupling loss</li> <li>• low price</li> <li>• easily hybrid</li> </ul>	<ul style="list-style-type: none"> <li>• high dimension (~cm)</li> <li>• material supply</li> </ul>
silica	-CVD FHD	<ul style="list-style-type: none"> <li>• low loss (&lt;0.01 dB/cm)</li> <li>• low coupling loss</li> <li>• stable</li> </ul>	<ul style="list-style-type: none"> <li>• high dimension (~ cm)</li> <li>• high cost</li> <li>• hard hybrid</li> <li>• polarization dependence</li> </ul>
SC	-InP substrate -MOCVD -epitaxy	<ul style="list-style-type: none"> <li>• small size (<math>\mu</math> mm)</li> <li>• integrable with active devices</li> </ul>	<ul style="list-style-type: none"> <li>• High loss (&gt;1 dB/cm)</li> <li>• high cost</li> <li>• complicate process</li> <li>• high coupling loss</li> </ul>

## Introduction

$$P_i(\omega) = P_i^0 + \chi_{ij}^{(1)} E_j(\omega) + \chi_{ijk}^{(2)} E_j(\omega) E_k(\omega) + \chi_{ijkl}^{(3)} E_j(\omega) E_k(\omega) E_l(\omega) + \dots$$



## Status

•Historically : 1970  $\chi^{(3)}$  → 1980  $\chi^{(2)}$  → 1990  $\chi^{(1)}$

Now : comercialized with low loss polymer(JDS Uniphase)  
 Future : hybrid/integration with high speed and/or amplifier

•North America :

DARP : amplification, interconnection

POINT, POLO : interconnection - Allied Signal, AMP, HP, Dupont

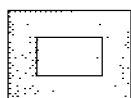
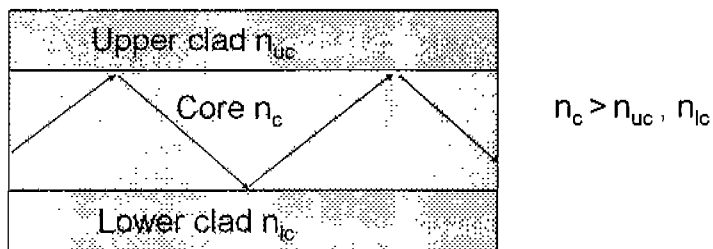
NIST : ATP(Advanced Technology Programs) : \$10M

•Japan : NTT, Hitachi

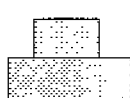
•Europe : RACE, ACTS project  
 AKZO : amplifier

•Domestic : ETRI, KAIST, Samsung, LG, Zen Photonics

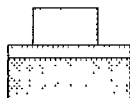
## Planar waveguide



buried channel



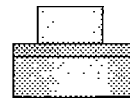
raised strip



rib guide



embedded strip

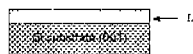


ridge guide

## Waveguide formation

- Reactive Ion etching
- Photobleaching
- Electric Poling
- Injection moulding

### 1. Spin coating of lower clad layer



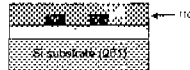
### 2. Spin coating of core layer



### 3. Patterning



### 4. Spin coating of upper clad layer



# RIE

## 1. substrate



## 2. Spin coating of lower clad layer



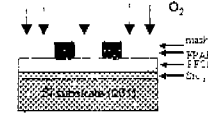
## 3. Spin coating of core layer



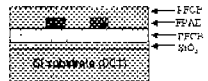
## 4. Photo lithography



## 5. RIE of core layer



## 6. Spin coating of upper clad layer



# Injection moulding

## 1. Deposit resist



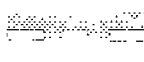
## 2. Patterning resist



## 3. Electro plating



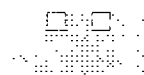
## 4. Metal mould



## 5. Injection moulding



## 6. Deforming



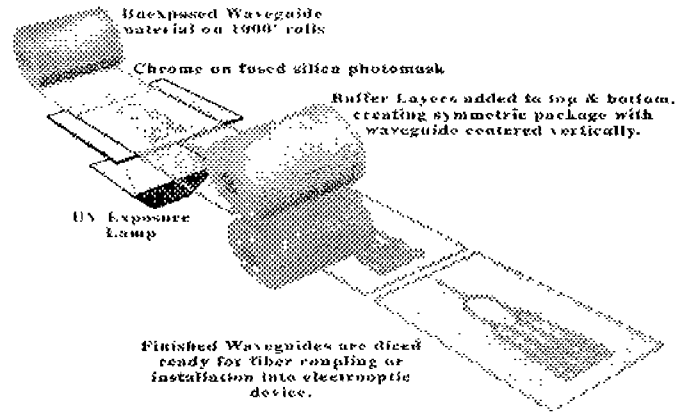
## 7. Core deposition



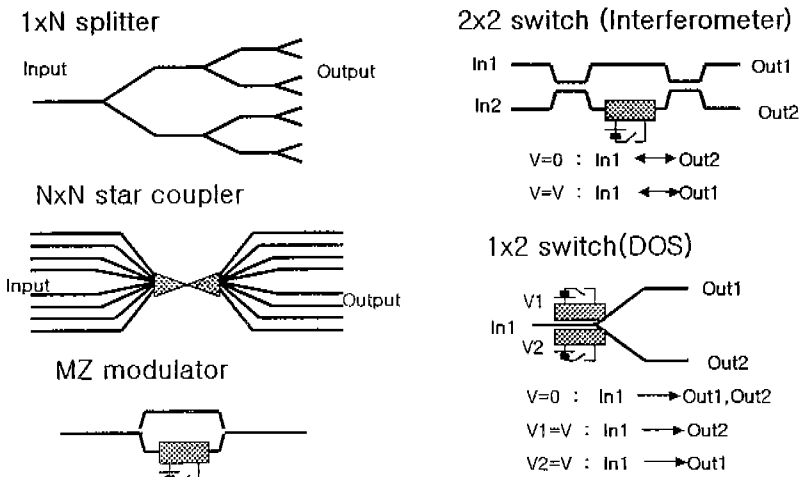
## 8. UC



## Fabrication of Devices(Multimode)

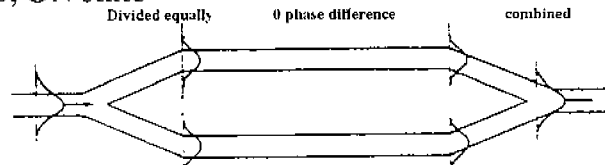


## Basic structure(I)

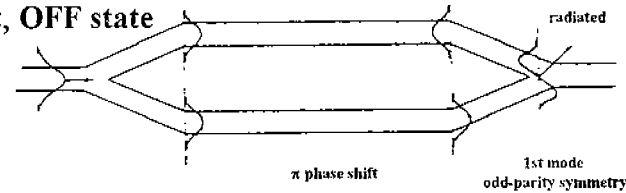


## Single Mode Waveguide Mach-Zehnder Modulator

$\Delta\phi = 0$ , ON state



$\Delta\phi = \pi$ , OFF state



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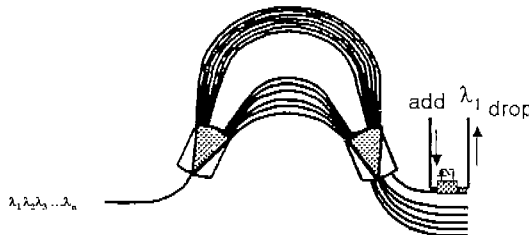
## Basic structure(II)

1xN AWG (Arrayed Waveguide Grating)



Wavelength switching:  
different  $\lambda \rightarrow$  different channel

ADM (Add Drop Multiplexer)



$V=0$  : AWG  
 $V=V$  : add or drop specific  $\lambda$

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## Requirements of optical waveguide polymers

- Low optical propagation loss at 1.3 or 1.55  $\mu\text{m}$  wavelength ( $<0.5$  dB/cm)
- Thermal stability at operating temperature ( $T_d > 300$  °C)
- Precise refractive index controllability
- Low birefringence (Polarization independent,  $\Delta n < 0.0002$ )
- Film formability, Multi-layer formability
- Thickness controllability, Dimensional flexibility
- Adhesion properties, Substrate compatibility
- Chemical & humidity resistance
- Gapfilling or planarization ability
- Cost effective technology (facile synthesis and processing)

## Optical Loss in the polymer waveguide

$$L_{\text{waveguide}} = L_{\text{absorption}} + L_{\text{scattering}} + L_{\text{extrinsic}}$$

$L_{\text{absorption}}$  = Electronic Absorption ( $n-\pi^*$ ,  $\pi-\pi^*$ , UV-visible)  
+ Vibration Absorption (NIR)

$L_{\text{scattering}}$  = Rayleigh Scattering (crystallinity of the polymer)

$L_{\text{extrinsic}}$  = Waveguide roughness, voids, crack, impurity

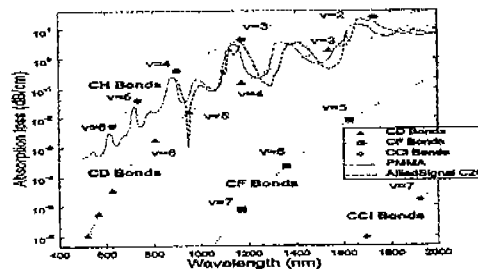
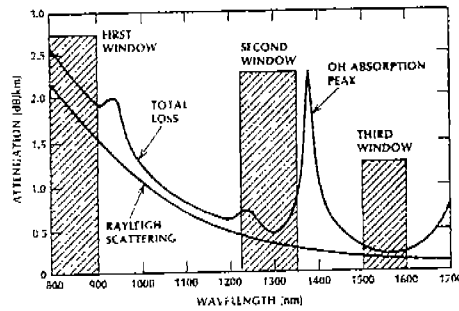


Fig. 3. Calculated absorption losses for various vibrational motions normalized to the observed absorptivity loss for PMMA. Also shown are experimental losses for PMMA and for a non-modified AlliedSignal polymer, an acrylate with a comparable concentration of CH bonds.

# Attenuation of Optical Fiber

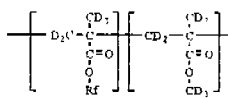
Optical Communications : 830 nm → 1300 nm → 1550 nm



## Low loss optical polymer development

Institute	Materials	Thermal Stability	Birefringence	Optical loss (dB/km)
NTT	Deuterated Fluoro acrylate polymer	T <sub>g</sub> = 114 °C	Δn < 10 <sup>-4</sup>	0.1 @ 1.3 μm 1.35 @ 1.55 μm
	Perfluorinated polyimides	T <sub>g</sub> = 309 °C	Δn = 0.008	0.3 @ 1.3 μm 0.6 @ 1.55 μm
	Silicone resin	T <sub>d</sub> = 400 °C	Δn = 10 <sup>-4</sup>	0.16 @ 1.3 μm 0.52 @ 1.55 μm
JDS Uniphase (Siac Systems)	Halogenated UV curable polycarbonate	T <sub>g</sub> = 150 °C	Unknown	~ 0.25 @ 1.55 μm (estimated)
Corning (AlliedSignal)	UV curable fluorinated acrylate	T <sub>d</sub> > 250 °C	Δn = 0.0008	0.03 @ 1.3 μm 0.06 @ 1.55 μm
Dow Chemical	Perfluorocyclobutane (PFPCB series)	T <sub>g</sub> = 400 °C	Δn = 0.0008 ~ 0.002	0.25 @ 1.3 μm
BFG/LMC	Fluorinated polycarbonate	T <sub>g</sub> = 290 ~ 360 °C	Δn = 0.0002	< 0.5 @ 1.55 μm
Ericsson/IBM	Fluorostyrene copolymer	T <sub>d</sub> > 250 °C	Δn = 4 x 10 <sup>-4</sup>	0.39 @ 1.32 μm 0.42 @ 1.55 μm
ZenPhotonics (ETRI)	Thermal curable fluorinated polyether	T <sub>d</sub> > 400 °C	Δn = 0.002 ~ 0.004	0.14 @ 1.3 μm 0.28 @ 1.55 μm
Samsung	Chloro fluoro polyimides	T <sub>g</sub> = 350 °C	Δn = 0.01	0.38 @ 1.55 μm

## NTT Materials



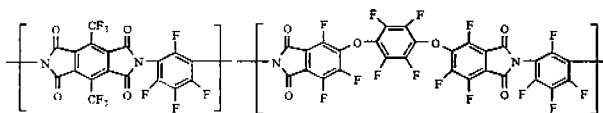
R<sub>f</sub> Perfluoroalkyl

PFPMA

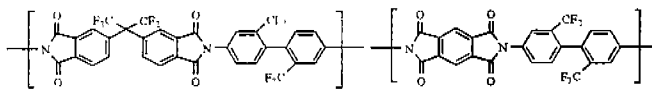


Deuterated polysiloxane.  
Phenylsilsesquioxane (PPSQ)

R = deuterated phenyl PhCl<sub>3</sub>



10FEDA/4FMPD



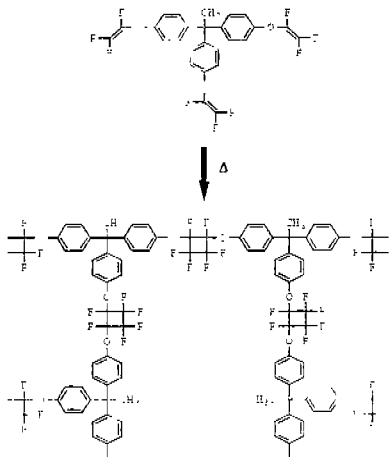
6FDA/TFDB

PMDA/TFDB

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## Dow Chemical Materials



PFCB

### Features of Dow Chemical

- Refractive index: 1.4898 @ 1.55 μm.
- Low birefringence:
  - ~ 0.0008 @ 1.55 μm, 230 °C.
  - ~ 0.0022 @ 1.55 μm, 250 °C.
- Low water absorption: 0.021 %
- Low intrinsic loss:
  - < 0.2 dB/cm @ 1.3 μm.
- High thermal stability: T<sub>g</sub> = 400 °C
- Mechanical flexibility and toughness
- Good gap fillability.

### References

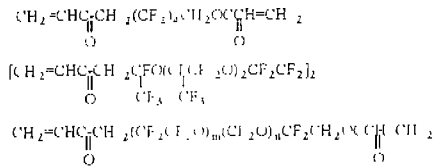
- K. Petermann et al. *Electron. Lett.*, 33, 518, (1997)
- A.P. Kennedy et al. *J. Polym. Sci., Polym. Chem.* 31, 3465 (1993)

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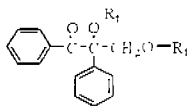
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# Corning (AlliedSignal) Materials

## Fluorinated Acrylate prepolymer



## Photoinitiators



R<sub>1</sub> = perfluoroalkyl

## Features of AlliedSignal

- Precise refractive index control continuous range 1.30 ~ 1.60
- Low birefringence: < 0.0008 @ 543.5nm
- High contrast photolithography suitable for UV laser curing
- Extremely low intrinsic loss loss below 0.03 dB/cm at 1.3 μm. loss below 0.05 dB/cm at 1.55 μm.
- High thermal stability: > 300 °C
- Mechanical flexibility and toughness

## References

- C. Wu et al. *US Patent*, 5,274,179 (1993)
- L. Eldada et al. *SPIE*, 3006, 344 (1997)
- L. Eldada et al. *J. Lightwave Technol.* 14, 1704 (1996)

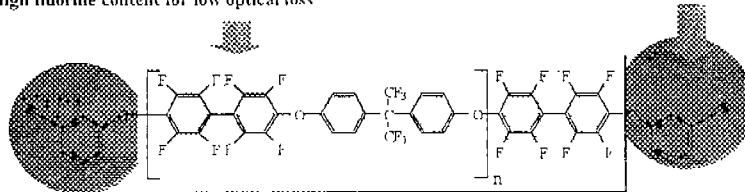


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# Basic chemical structure

## Fluorinated poly(arylene ether)s with ethynyl group

- |  |                               |
|--|-------------------------------|
| - High thermal stability                     | - Good chemical resistance    |
| - Good mechanical properties                 | - Good gapfilling ability     |
| - Low moisture absorption                    | - Increased adhesion property |
| - low dielectric constant                    | - Good processability         |
| - High fluorine content for low optical loss |                               |



↓ Thermal curing

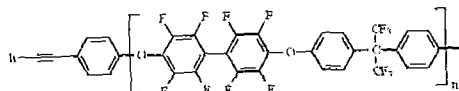
Crosslinked FPAE-EP polymers



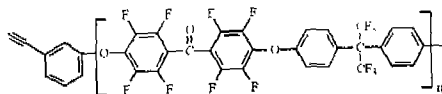
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## Synthesized Materials

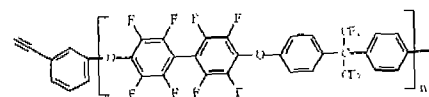
### Fluorinated Polyether series



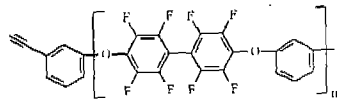
FPAE-PEP;  $M_n = 8,540$ ,  $M_w/M_n = 1.87$   
 $T_g > 320$  °C



FPEK-EP;  $M_n = 6,700$ ,  $M_w/M_n = 1.76$   
 $T_g > 235$  °C



FPAE-EP;  $M_n = 8,940$ ,  $M_w/M_n = 1.56$   
 $T_g > 240$  °C

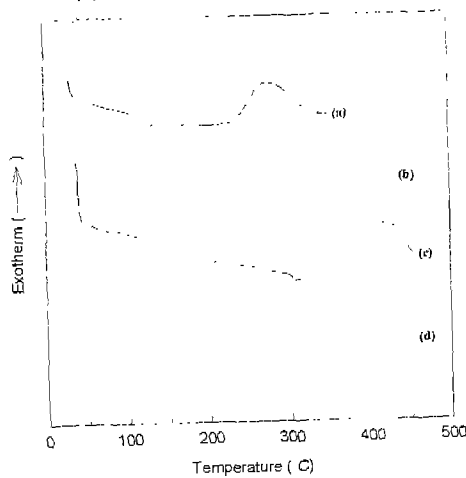


FPAE(RC100)-EP;  $M_n = 8,680$ ,  $M_w/M_n = 1.61$   
 $T_g > 240$  °C

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## DSC thermograms



(a) = first scan of the FPEK-EP  
 (b) = second scan of the FPEK-EP  
 (c) = first scan of the FPAE-PEP  
 (d) = second scan of the FPAE-PEP  
 scan rate = 10 °C/min.

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## TGA thermograms

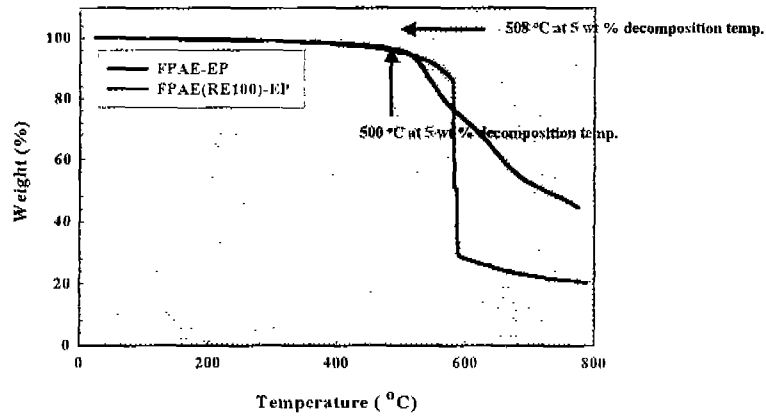


Fig. TGA curve of the polymers under nitrogen at a heating rate of 10 °C/min

## Refractive index control

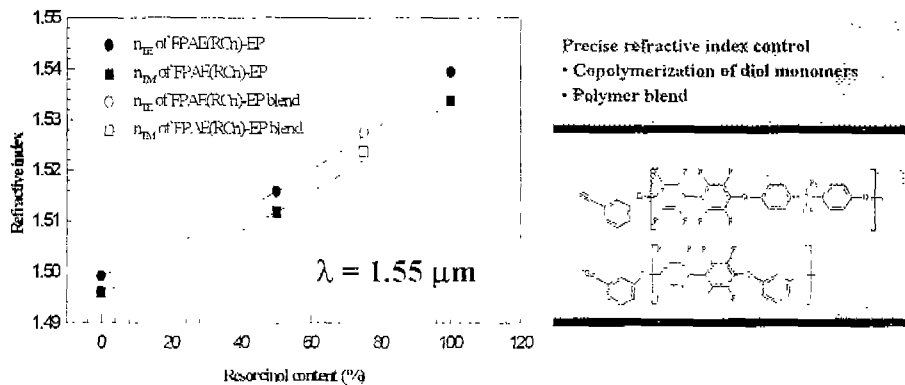


Fig. Refractive index of the FPAAE-EP polymers as a contents of resorcinol group

## Long-term refractive index stability

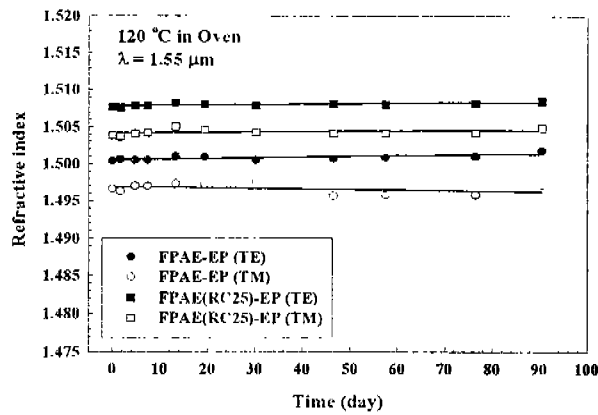


Fig. Refractive index change of the FPAAE-EP films during high temperature storage at 120 °C

## Optical propagation loss

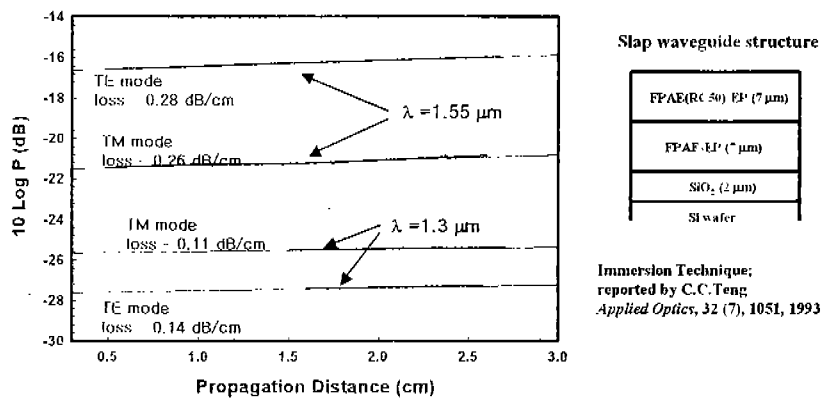


Fig. Optical propagation loss of slap waveguide FPAAE(RC50)-EP film

## Summary of developed Polymers

<b>Optical Properties</b>	Propagation loss (waveguide)	0.2 ~ 0.3 dB/cm @ 1.55 mm 0.1 ~ 0.15 dB/cm @ 1.30 mm
	Refractive index range	1.48 ~ 1.54 @ 1.55 mm
	Intrinsic birefringence	0.002 ~ 0.004
	Thermo-optic coefficient	$> -1 \times 10^{-4}$
<b>Thermal Properties</b>	Weight loss temp. (2 %)	480 °C
	T <sub>m</sub> (after curing)	none
	Processing Temp.	< 250 °C
<b>Solution Properties</b>	Solution Viscosity	250 ~ 500 cps
	Solid content	35 wt %
<b>Chemical Properties</b>	Solvent resistant	No cracking
	Hydrolytic stability	No cracking
	Water absorption	< 1 % (100 °C, 12 hr.)
<b>Electrical Properties</b>	Dielectric constant	< 2.6 (10 kHz, 30 °C)
	Loss tangent	< 0.001

## Development Optical Devices at ZEN, ETRI

- Optical Switch**
- Optical Variable Attenuator**
- Wavelength Mux/Demux**
- Tunable Wavelength Filter**

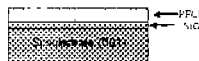


## Device fabrication procedure

### 1. substrate



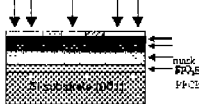
### 2. Spin coating of lower clad layer



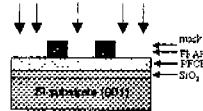
### 3. Spin coating of core layer



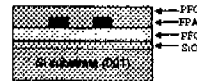
### 4. Photo lithography



### 5. RIE of core layer



### 6. Spin coating of upper clad layer



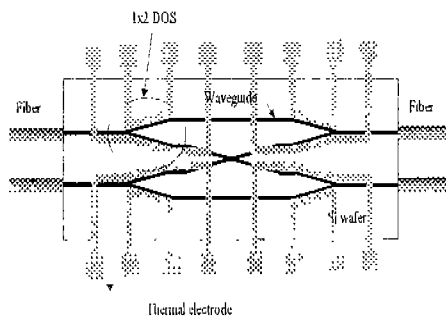
### 7. Fiber coupling



### 8. Packaging/Stability



## Optical Switch(DOS)

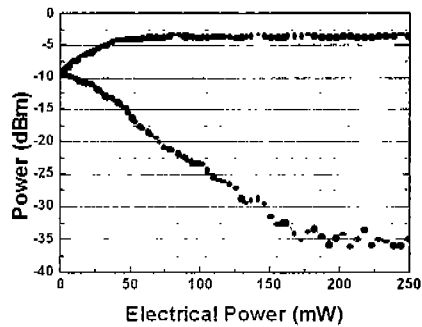


### Applications

- WDM system
- ADM, OXC, by pass, optical system
- Radar system
- RF PAA(Phase Arrayed Antenna)

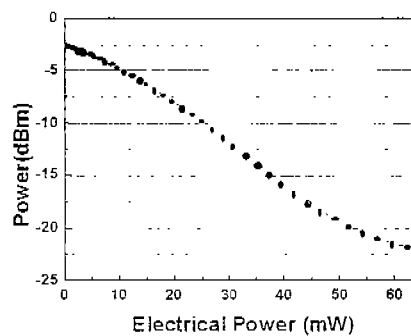
## 2x2 Digital Optical Switch

- Four 1x2 switches
- Insertion Loss : < 3.5 dB
- Cross-talk : > 30 dB
- Switching Power : < 300 mW
- Switching time : < 3 nsec
- PDL : < 0.3 dB
- Simple connection  
(3 electrical ports)

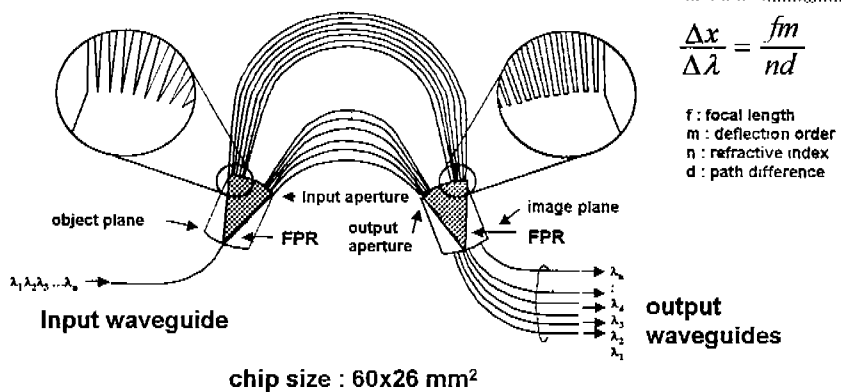


## Variable Attenuator

- Insertion Loss : < 2.5 dB
- Attenuation range : > 20 dB
- Driving power : < 65 mW
- Response time : < 5 msec
- Simple connection  
(2 electrical ports)

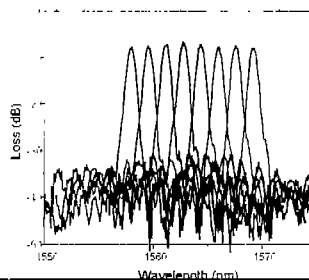
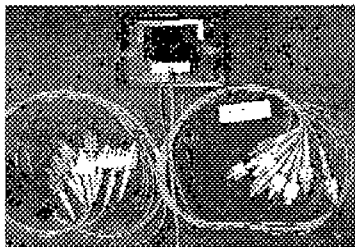


## Wavelength Mux/Demus Structure



## AWG

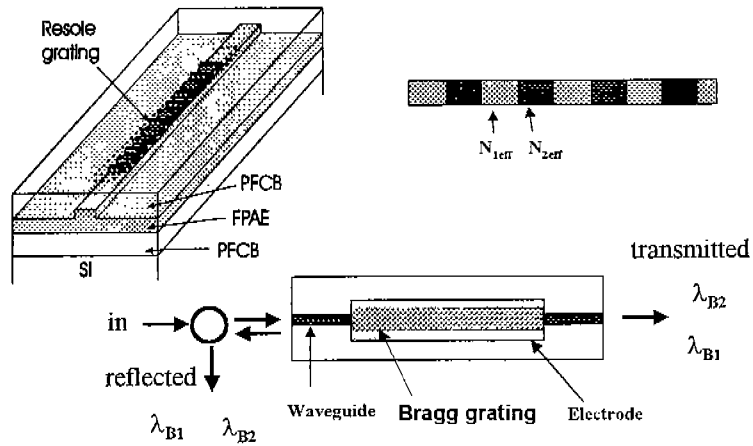
### AWG wavelength multiplexer



#### Characteristics:

channel: 1x8, size: 40x15 mm<sup>2</sup>, center wavelength: 1562 nm,  
 channel spacing: 1.6 nm, cross-talk: -25 dB, insertion loss: 7~8 dB

## Basic structure for TF

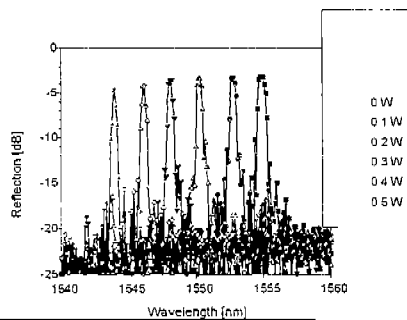
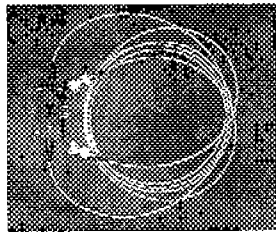


ZENPHOTONICS

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## TF

### Tunable wavelength filter



#### Characteristics:

Tuning range: >10 nm, band width: 0.4 nm, insertion loss: 3.2 dB  
 Tuning power: 20 nm/W, loss variation : 1 dB

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# Future possibilities

